

Appl. No. 10/660,866  
Amendment dated March 5, 2005

PATENT

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

Claims 1.-8. (canceled)

Claim 9. (currently amended) A method of making a chip device, the method comprising:  
    providing a die;  
    providing a leadframe including a die attach cavity and a plurality of dimples defined around a periphery of the leadframe, the die attach cavity having substantially the same thickness as the die;  
    placing solder balls into the dimples; and  
    flipping the die into the die attach cavity and attaching it the die therein,  
    wherein the die comprises a MOSFET.

Claim 10. (original) The method of claim 9 wherein the die provided is a bumped die.

Claim 11. (canceled)

Claim 12. (previously presented) The method of claim 9 further comprising placing solder on the die.

Claim 13. (previously presented) The method of claim 9 wherein the leadframe comprises a copper based alloy.

Claim 14. (previously presented) The chip device of claim 9 wherein the leadframe includes a solderable coating.

Claim 15. (previously presented) The method of claim 9 wherein the die comprises source and gate connections.

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Claim 16. (previously presented) The method of claim 9 wherein the leadframe comprises a Ni-Pd coating.

Claim 17. (previously presented) The method of claim 9 wherein the die has solder balls thereon to serve as source and gate connections.

Claim 18. (previously presented) The method of claim 9 wherein the step of attaching the die is performed such that the die is coplanar with a top surface of the leadframe.

Claim 19. (previously presented) The method of claim 9 further comprising the step of adding a solderable coating to the leadframe.

Claim 20. (previously presented) The method of claim 9 wherein the leadframe is conductive.

Claim 21. (previously presented) The method of claim 20 wherein the conductive leadframe comprises a copper based alloy.